



PRELIMINARY

DS90CR281/DS90CR282 28-Bit Channel Link

General Description

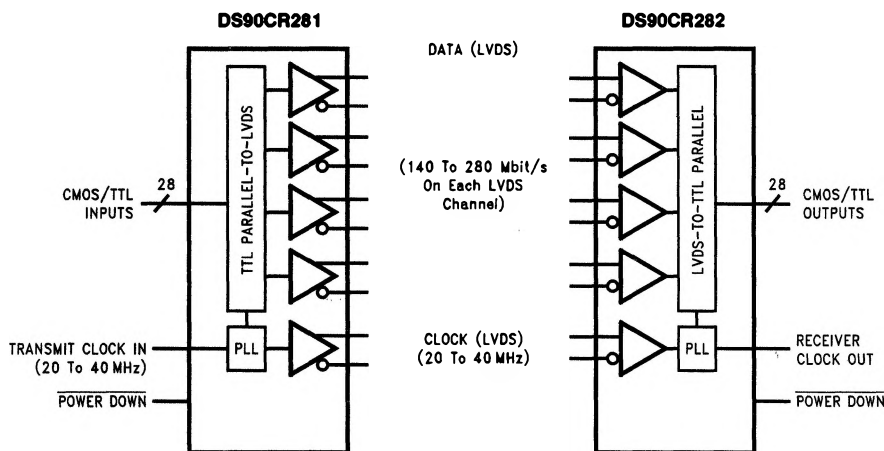
The DS90CR281 transmitter converts 28 bits of CMOS/TTL data into four LVDS (Low Voltage Differential Signaling) data streams. A phase-locked transmit clock is transmitted in parallel with the data streams over a fifth LVDS link. Every cycle of the transmit clock 28 bits of input data are sampled and transmitted. The DS90CR282 receiver converts the LVDS data streams back into 28 bits of CMOS/TTL data. At a transmit clock frequency of 40 MHz, 28 bits of TTL data are transmitted at a rate of 280 Mbps per LVDS data channel. Using a 40 MHz clock, the data throughput is 140 Megabytes per second.

The 28 CMOS/TTL inputs can support a variety of signal combinations. For example, 7 4-bit nibbles or 3 9-bit (byte + parity) and 1 control.

Features

- Up to 140 Mbyte/sec bandwidth
- 345 mV swing LVDS devices for low EMI
- Low power CMOS design
- Power-down mode
- PLL requires no external components
- Low profile 56-lead TSSOP package
- Rising edge data strobe
- Narrow bus reduces cable size

Block Diagrams

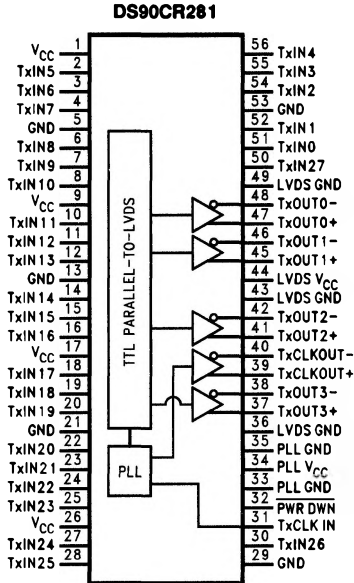


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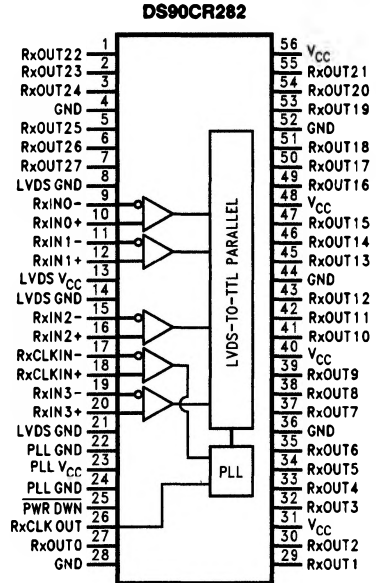
Order Number DS90CR281MTD
See NS Package Number MTD56

Order Number DS90CR282MTD
See NS Package Number MTD56

Connection Diagrams



TL/F/12638-2



TL/F/12638-3

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	-0.3V to +6V
CMOS/TTL Input Voltage	-0.3V to ($V_{CC} + 0.3V$)
CMOS/TTL Output Voltage	-0.3V to ($V_{CC} + 0.3V$)
LVDS Receiver Input Voltage	-0.3V to ($V_{CC} + 0.3V$)
LVDS Driver Output Voltage	-0.3V to ($V_{CC} + 0.3V$)
LVDS Output Short Circuit Duration	continuous
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 4 sec.)	+260°C

Maximum Package Power Dissipation @ +25°C

MTD56(TSSOP) Package:

DS90CR281 1.63W

DS90CR282 1.61W

Package Derating: DS90CR281 12.5 mW/°C above +25°C

DS90CR282 12.4 mW/°C above +25°C

This device does not meet 2000V ESD rating (Note 4).

Recommended Operating Conditions

	Min	Nom	Max	Units
Supply Voltage (V_{CC})	4.5	5.0	5.5	V
Operating Free Air Temperature (T_A)	-10	+25	+70	°C
Receiver Input Range	0	2.4	V	

Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Units
CMOS/TTL DC SPECIFICATIONS						
V_{IH}	High Level Input Voltage		2.0		V_{CC}	V
V_{IL}	Low Level Input Voltage		GND		0.8	V
V_{OH}	High Level Output Voltage	$I_{OH} = -0.4$ mA	3.8	4.9		V
V_{OL}	Low Level Output Voltage	$I_{OL} = 2$ mA		0.1	0.3	V
V_{CL}	Input Clamp Voltage	$I_{CL} = -18$ mA		-0.79	-1.5	V
I_{IN}	Input Current	$V_{IN} = V_{CC}, GND, 2.5V$ or $0.4V$		±5.1	±10	μA
I_{OS}	Output Short Circuit Current	$V_{OUT} = 0V$			-120	mA
LVDS DRIVER DC SPECIFICATIONS						
V_{OD}	Differential Output Voltage	$R_L = 100\Omega$	250	290	450	mV
ΔV_{OD}	Change in V_{OD} between Complementary Output States				35	mV
V_{CM}	Common Mode Voltage		1.1	1.25	1.375	V
ΔV_{CM}	Change in V_{CM} between Complementary Output States				35	V
V_{OH}	High Level Output Voltage			1.3	1.6	V
V_{OL}	Low Level Output Voltage		0.9	1.07		V
I_{OS}	Output Short Circuit Current	$V_{OUT} = 0V, R_L = 100\Omega$		-2.9	-5	mA
I_{OZ}	Output TRI-STATE® Current	Power Down = $0V, V_{OUT} = 0V$ or V_{CC}		±1	±10	μA
LVDS RECEIVER DC SPECIFICATIONS						
V_{TH}	Differential Input High Threshold	$V_{CM} = +1.2V$			+100	mV
V_{TL}	Differential Input Low Threshold		-100			mV
I_{IN}	Input Current	$V_{IN} = +2.4V$	$V_{CC} = 5.5V$		±10	μA
		$V_{IN} = 0V$			±10	μA

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" specify conditions for device operation.

Note 2: Typical values are given for $V_{CC} = 5.0V$ and $T_A = +25^\circ C$.

Note 3: Current into device pins is defined as positive. Current out of device pins is defined as negative. Voltages are referenced to ground unless otherwise specified (except V_{OD} and ΔV_{OD}).

Note 4: ESD Rating: HBM (1.5 kΩ, 100 pF)
 PLL $V_{CC} \geq 1000V$
 All other pins $\geq 2000V$
 EIAJ (0Ω, 200 pF) $\geq 150V$

Electrical Characteristics (Continued)

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Units
TRANSMITTER SUPPLY CURRENT						
I _{CCTW}	Transmitter Supply Current, Worst Case	R _L = 100Ω, C _L = 5 pF, Worst Case Pattern (Figures 1, 2)	f = 32.5 MHz	34	46	mA
			f = 37.5 MHz	36	48	mA
I _{CCTZ}	Transmitter Supply Current, Power Down	Power Down = Low		1	10	μA

RECEIVER SUPPLY CURRENT

I _{CCRW}	Receiver Supply Current, Worst Case	C _L = 8 pF, Worst Case Pattern (Figures 1, 3)	f = 32.5 MHz	55	75	mA
			f = 37.5 MHz	60	80	mA
I _{CCRZ}	Receiver Supply Current, Power Down	Power Down = Low		1	10	μA

Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter		Min	Typ	Max	Units
LLHT	LVDS Low-to-High Transition Time (Figure 2)			0.75	1.5	ns
LHLT	LVDS High-to-Low Transition Time (Figure 2)			0.75	1.5	ns
CLHT	CMOS/TTL Low-to-High Transition Time (Figure 3)			3.5	6.5	ns
CHLT	CMOS/TTL High-to-Low Transition Time (Figure 3)			2.7	6.5	ns
TCIT	TxCLK IN Transition Time (Figure 4)				8	ns
TCCS	TxOUT Channel-to-Channel Skew (Note A) (Figure 5)				350	ps
TSSPW	Tx Sub-Symbol Pulse Width (Figure 5)	f = 20 MHz	5.5	7	8	ns
RCCS	RxIN Channel-to-Channel Skew (Note B)				700	ps
TCIP	TxCLK IN Period (Figure 6)		25	T	50	ns
TCIH	TxCLK IN High Time (Figure 6)		0.35T	0.5T	0.65T	ns
TCIL	TxCLK IN Low Time (Figure 6)		0.35T	0.5T	0.65T	ns
TSTC	TxIN Setup to TxCLK IN (Figure 6)		8			ns
THTC	TxIN Hold to TxCLK IN (Figure 6)		2.5	2		ns
RCOP	RxCLK OUT Period (Figure 7)		25	T	50	ns

Note A: This limit based on bench characterization.**Note B:** This limit assumes a maximum cable skew of 350 ps.

Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified (Continued)

Symbol	Parameter		Min	Typ	Max	Units
RCOH	RxCLK OUT High Time (Figure 7)	f = 20 MHz	19			ns
		f = 40 MHz	6			ns
RCOL	RxCLK OUT Low Time (Figure 7)	f = 20 MHz	21.5			ns
		f = 40 MHz	10.5			ns
RSRC	RxOUT Setup to RxCLK OUT (Figure 7)	f = 20 MHz	14			ns
		f = 40 MHz	4.5			ns
RHRC	RxOUT Hold to RxCLK OUT (Figure 7)	f = 20 MHz	16			ns
		f = 40 MHz	6			ns
TCCD	TxCLK IN to TxCLK OUT Delay @ 25°C, V _{CC} = 5.0V (Figure 8)		5		9.7	ns
RCCD	RxCLK IN to RxCLK OUT Delay @ 25°C, V _{CC} = 5.0V (Figure 9)		7.6		11.9	ns
TPLLS	Transmitter Phase Lock Loop Set (Figure 10)				10	ms
RPLLS	Receiver Phase Lock Loop Set (Figure 11)				10	ms

AC Timing Diagrams

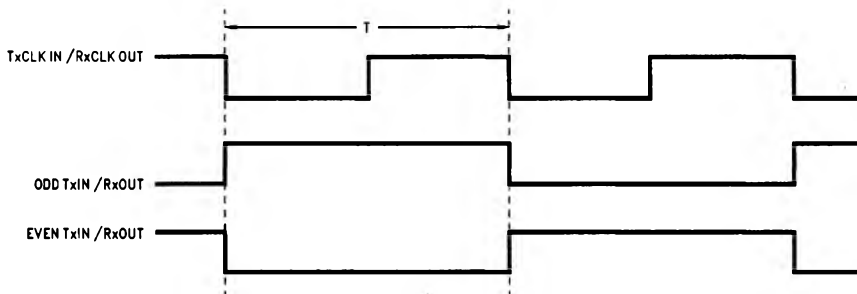
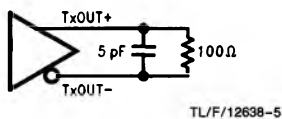


FIGURE 1. "WORST CASE" Test Pattern

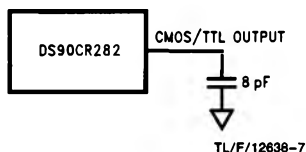
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FIGURE 2. DS90CR281 (Transmitter) LVDS Output Load and Transition Timing

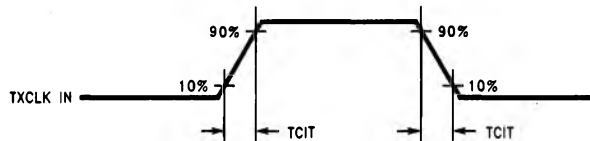
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TL/F/12638-7

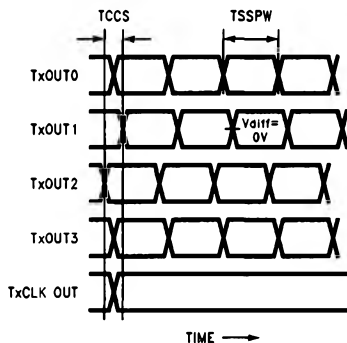
FIGURE 3. DS90CR282 (Receiver) CMOS/TTL Output Load and Transition Timing

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TL/F/12638-9

FIGURE 4. DS90CR281 (Transmitter) Input Clock Transition Time



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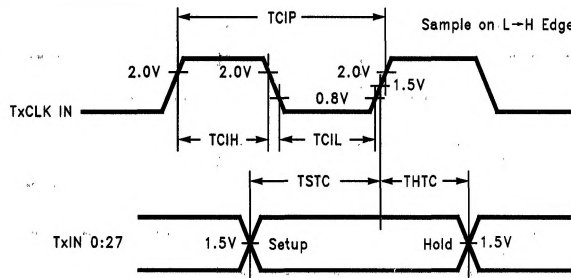
FIGURE 5. DS90CR281 (Transmitter) Channel-to-Channel Skew and Pulse Width

Note 1: Measurements at $V_{diff} = 0V$

Note 2: TCCS measured between earliest and latest initial LVDS edges.

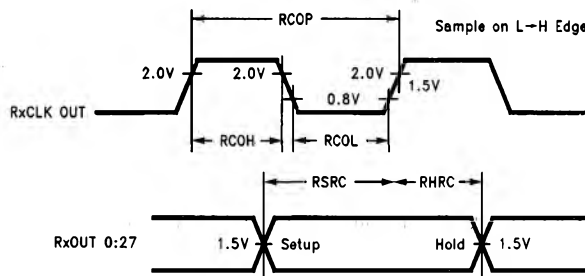
Note 3: TxCLK OUT Differential Low $\rightarrow$ High Edge

AC Timing Diagrams (Continued)



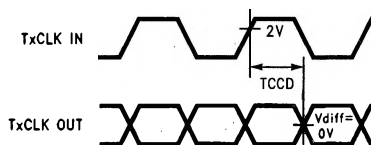
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FIGURE 6. DS90CR281 (Transmitter) Setup/Hold and High/Low Times



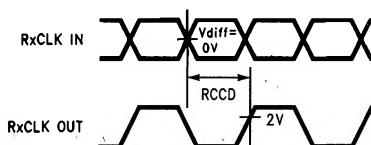
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FIGURE 7. (Receiver) DS90CR282 Setup/Hold and High/Low Times



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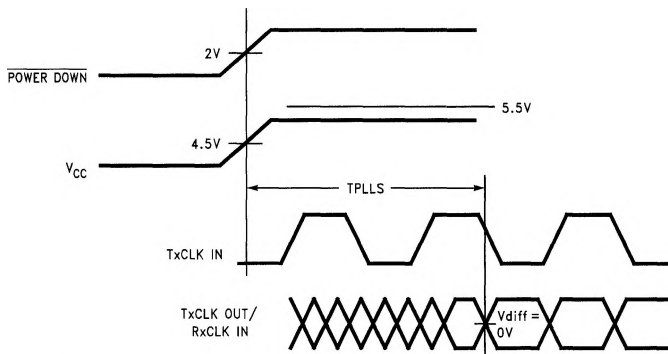
FIGURE 8. DS90CR281 (Transmitter) Clock In to Clock Out Delay



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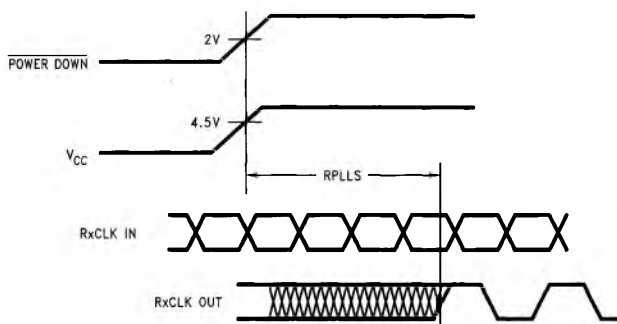
FIGURE 9. DS90CR282 (Receiver) Clock In to Clock Out Delay

AC Timing Diagrams (Continued)



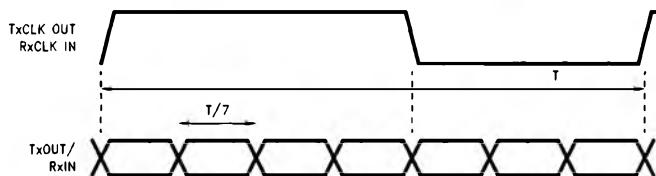
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FIGURE 10. DS90CR281 (Transmitter) Phase Lock Loop Set Time



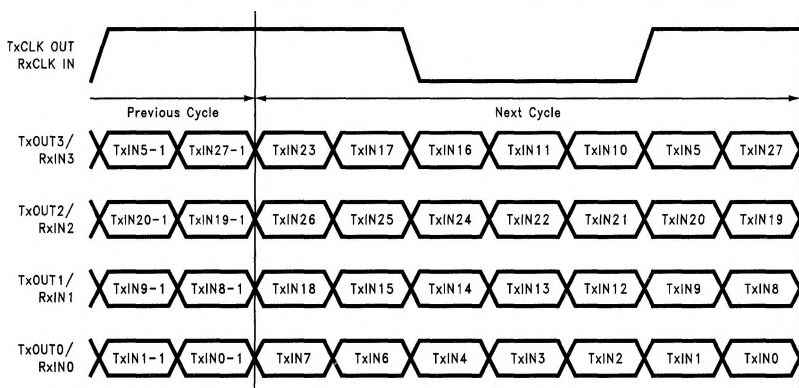
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FIGURE 11. DS90CR282 (Receiver) Phase Lock Loop Set Time



TL/F/12638-17

FIGURE 12. Seven Bits of LVDS in One Clock Cycle



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FIGURE 13. 28 Parallel TTL Data Inputs Mapped to LVDS Outputs (DS90CR281)

DS90CR281 Pin Description—Channel Link Transmitter

Pin Name	I/O	No.	Description
TxIN	I	28	TTL Level inputs
TxOUT +	O	4	Positive LVDS differential data output
TxOUT –	O	4	Negative LVDS differential data output
TxCLK IN	I	1	TTL level clock input. The rising edge acts as data strobe
TxCLK OUT +	O	1	Positive LVDS differential clock output
TxCLK OUT –	O	1	Negative LVDS differential clock output
PWR DOWN	I	1	TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down
V _{CC}	I	4	Power supply pins for TTL inputs
GND	I	5	Ground pins for TTL inputs
PLL V _{CC}	I	1	Power supply pin for PLL
PLL GND	I	2	Ground pins for PLL
LVDS V _{CC}	I	1	Power supply pin for LVDS outputs
LVDS GND	I	3	Ground pins for LVDS outputs

DS90CR282 Pin Description—Channel Link Receiver

Pin Name	I/O	No.	Description
RxIN +	I	4	Positive LVDS differential data inputs
RxIN –	I	4	Negative LVDS differential data inputs
RxOUT	O	28	TTL level outputs
RxCLK IN +	I	1	Positive LVDS differential clock input
RxCLK IN –	I	1	Negative LVDS differential clock input
RxCLK OUT	O	1	TTL level clock output. The rising edge acts as data strobe
PWR DOWN	I	1	TTL level input. Assertion (low input) TRI-STATES the outputs, ensuring low current at power down
V _{CC}	I	4	Power supply pins for TTL outputs
GND	I	5	Ground pins for TTL outputs
PLL V _{CC}	I	1	Power supply for PLL
PLL GND	I	2	Ground pin for PLL
LVDS V _{CC}	I	1	Power supply pin for LVDS inputs
LVDS GND	I	3	Ground pins for LVDS inputs